



I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as First Class Mail, in an envelope addressed to: MS AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: May 22, 2007 Signature: \_\_\_\_\_

(Nikolaus P. Schibli)

**EXPEDITED PROCEDURE**

Group Art Unit: 1765

Docket No.: TESSERA 3.0-313

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: :  
Light et al. :  
Application No.: 10/771,252 : Group Art Unit: 1765  
Filed: February 3, 2004 : Examiner: S. Ahmed  
For: METHOD FOR MAKING A :  
MICROELECTRONIC PACKAGE USING :  
PRE-PATTERNED, REUSABLE MOLDAND :  
METHOD FOR MAKING THE MOLD :

**AMENDMENT FILED CONCURRENTLY WITH**  
**A REQUEST FOR CONTINUED EXAMINATION (RCE)**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated  
December 5, 2006, finally rejecting claims 1-40, please amend  
the above-identified U.S. patent application as follows:

5/29/07

AF 701201

L02.00 00